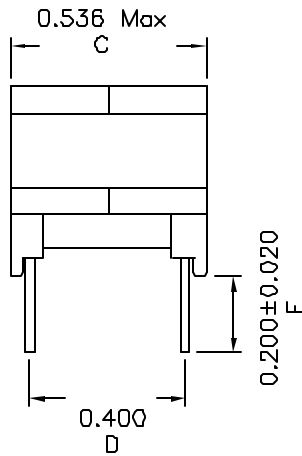
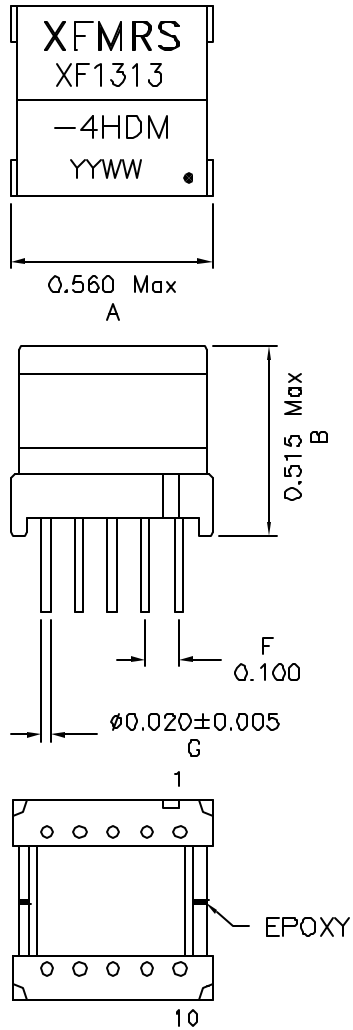


### 1. Dimensions:

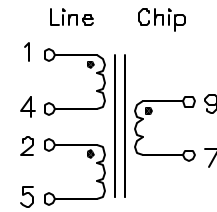


**Notes:**

1. Solderability: Leads shall meet MIL-STD-202G, Method 208H for solderability.
2. Flammability: UL94V-0
3. ASTM oxygen index: > 28%
4. Insulation System: Class F 155°C. UL file E151556
5. Operating Temperature Range: All listed parameters are to be within tolerance from -40°C to +85°C
6. Storage Temperature Range: -55°C to +125°C
7. Aqueous wash compatible
8. Electrical and mechanical specifications 100% tested
9. RoHS Compliant Component
10. UL1950 approved to Supplementary Insulation requirements for a working voltage up to 300V, file #E165866.

DOC. REV C/3

### 2.Schematic:



### 3.Electrical Specifications: @25°C

- OCL: Pins 1-5 3.0mH ±6% @10KHz 0.1V
- LL: Pins 1-5 11uH Max @100KHz 100mV  
(Tie Pins 2-4, Pins 7-9)
- Turns Ratio: Line:Chip = 2CS:1±1%
- DCR: 2.5 Ohms Max (Line)
- DCR: 1.0 Ohm Max (Chip)
- DC Current: 100mA
- THD: 70dB Min. @40KHz
- RETURN LOSS: 20dB Min. @40KHz-200KHz
- INSERTION LOSS: ±0.4dB Max @200KHz
- LONGITUDINAL BALANCE: 53dB Min. @40KHz-200KHz
- FREQ RESP: ±0.1dB, 40KHz-200KHz
- Isolation Voltage: 2500Vrms (Chip to Line)

**PROPRIETARY**

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<b>XFMRS Inc</b> www.xfmrs.com	Title: HDSL TRANSFORMER		
	UNLESS OTHERWISE SPECIFIED TOLERANCES: .xxx ±0.010 Dimensions in INCH	P/N: XF1313-4HDM DWN.	REV. C 罗振江
SHEET 1 OF 1	APP.	廖玉坤	Jul-13-07
		MS	Jul-13-07